

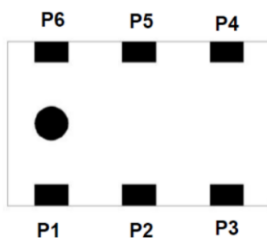
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

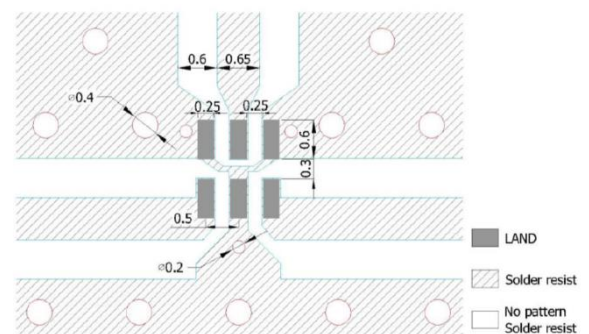
NO.	Specification			
1	Frequency range (MHz)	2400~2500	4900~5950	
2	Insertion Loss (dB) @25°C	0.85	1.10	
3	Return Loss (dB)	15 min.	15 min.	
4	Impedance (Ω)	50	50	
5	Attenuation (dB)	700~1200MHz	20	-
		1200~1300 MHz	20	27
		1300~1500 MHz	-	27
		1600~2000 MHz	-	26
		2300~3000 MHz	-	25
		4800~5000 MHz	25	-
		7200~7500 MHz	30	-
		10000~11800MHz	-	28
6	Isolation (dB)	2400~2500 MHz	-	30 min.
		4900~5950 MHz	25 min.	-
Operating & Storage Condition (Component)				
Operation Temperature Range: -40°C ~ +85°C				
Storage Temperature Range: -40°C~ +85°C				
Storage Condition before Soldering (Included packaging material)				
Storage Temperature Range: +5 ~ +40 °C				
Humidity: 30 to 70% relative humidity				

Construction



PIN	Connection	PIN	Connection
P1	Higher Port	P4	GND
P2	GND	P5	Antenna Input
P3	Low Port	P6	GND

Mounting Considerations



Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

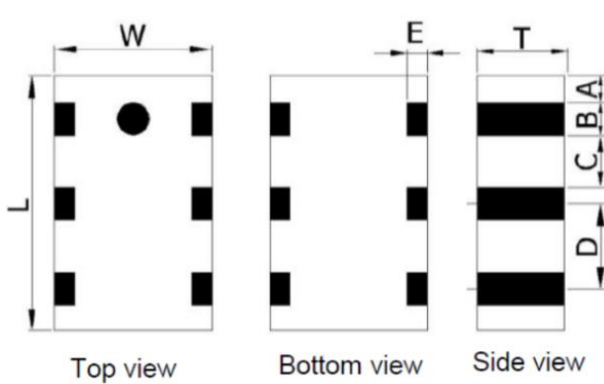
Yantel Corporation

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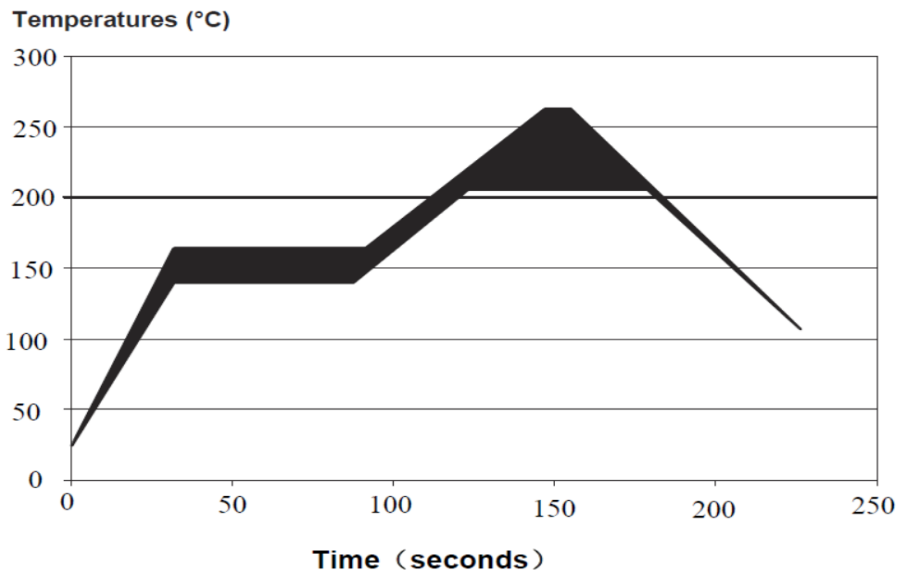
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For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com

Dimensions

Figure	Symbol	Dimension (mm)
 <p>Top view Bottom view Side view</p>	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6 ± 0.10
	A	0.2 ± 0.10
	B	0.2 ± 0.10
	C	0.3 ± 0.10
	D	0.5 ± 0.10
E	0.15 ± 0.10	

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery)

*Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.